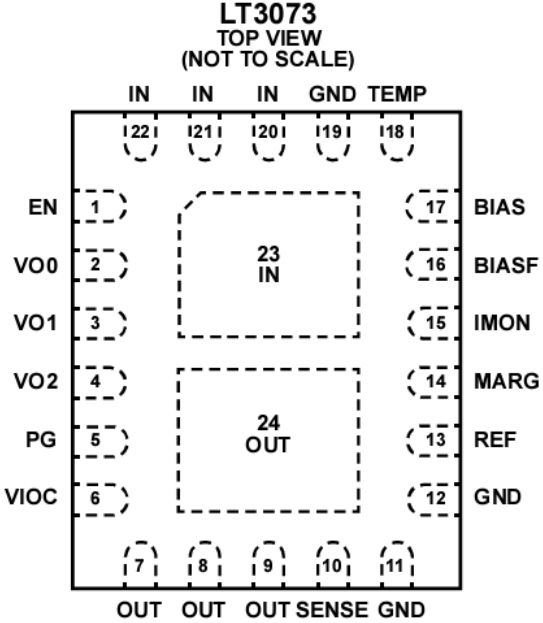




# LT3073 Die Thickness and Thermal Parameter Change

Chaitrali Joshi 9/30/2024

# Data Sheet Mark up



$T_{jmax} = 110.6C,$   
 $\theta_{JA} = 38 C/W$   
 $\theta_{JC top} = 50 C/W$

**NOTES**  
 1. EXPOSED PAD. SOLDER PINS 23 AND 24 TO THE PCB FOR BETTER THERMAL PERFORMANCE.

LQFN PACKAGE  
 22-LEAD (3mm X 4mm)  
 ~~$T_{JMAX} = 125^{\circ}C, \theta_{JA} = 36^{\circ}C/W, \theta_{JCBOT} = 5^{\circ}C/W, \theta_{JCTOP} = 27^{\circ}C/W$~~

**Figure 3. Pin Configuration**